

## J1-Series for Automotive Applications

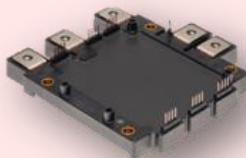
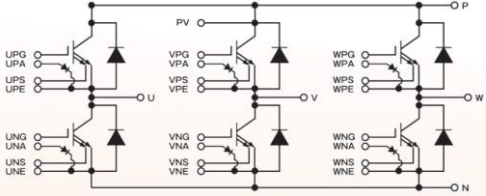
Lightweight, Compact Power Modules for xEV Inverters  
Enhancing Efficiency and Reliability

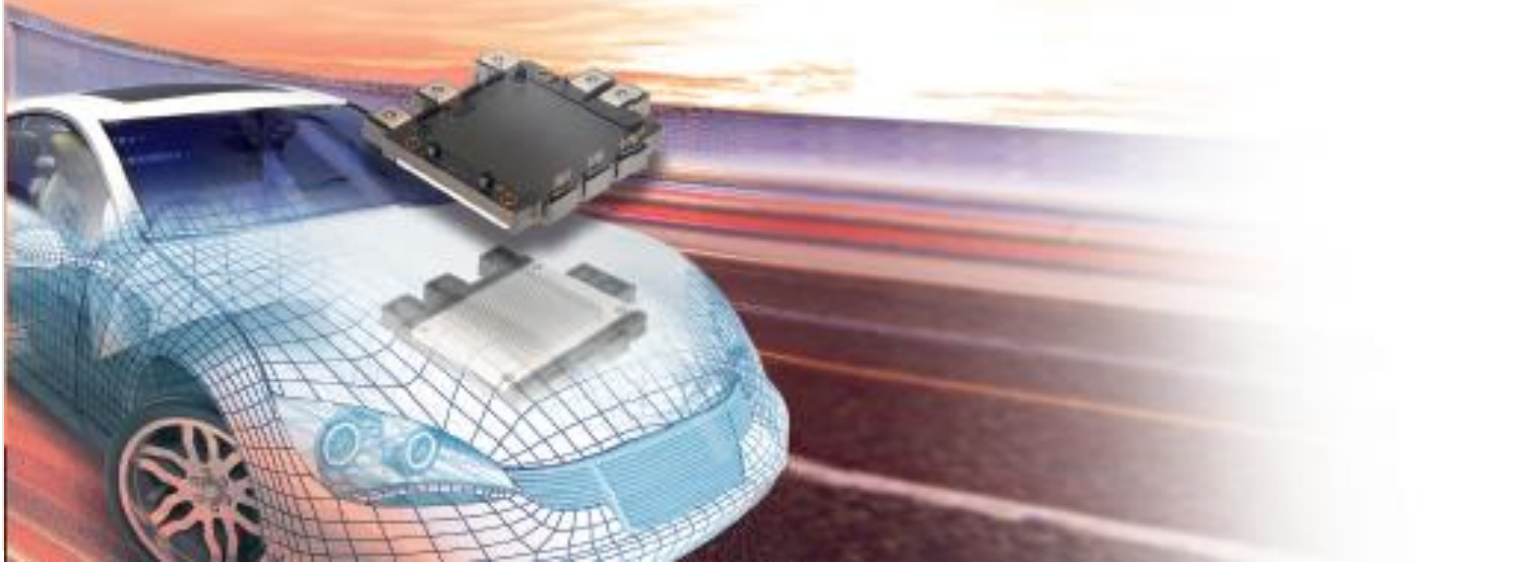
### Features

- ❑ Compact highly reliable light weight 6in1 package for automotive inverters
- ❑ Direct water-cooling structure with Aluminum cooling fins
- ❑ Direct Lead Bonding (DLB) package (wire bond less) ensures high reliability
- ❑ Low power loss 7th-Generation CSTBT™\* chip technology
- ❑ On-chip temperature and current sensors
- ❑ Pb-free, RoHS-compliant structure

\* CSTBT™: Carrier Stored Trench-Gate Bipolar Transistor



$V_{CES}$ [V] (@ $T_j = -40^\circ\text{C}$ )	$I_C$ [A]	Type Name	Package	Circuit Diagram
650	600	CT600CJ1A060-A	115.7 x 120 mm <sup>2</sup> 	
	700	CT700CJ1A060-A		



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